

Update Notification
Document #: FPCN20649X1
Issue Date: 15 December 2015

Title of Change:	Update to FPCN20649 - exclude NSS30101LT1G & NSS30100LT1G from Copper Wire conversion
Proposed first ship date:	15 December 2015
Contact information:	Contact your local ON Semiconductor Sales Office or <alex.zhang@onsemi.com></alex.zhang@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <s1016z@onsemi.com></s1016z@onsemi.com>
Type of notification:	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other
Change Sub-Category(s): □ Datasheet/Product Doc change □ Manufacturing Site Change/Addition □ Material Change □ Shipping/Packaging/Marking □ Manufacturing Process Change □ Other: □ Other:	
Sites Affected: ☐ All site(s) ☐ not ap	plicable ON Semiconductor site(s): ON Leshan, China External Foundry/Subcon site(s)
Description and Purpose:	
ON Semiconductor is notifying customer that NSS30101LT1G and NSS30100LT1G will be excluded and shall not undergo the Gold to Copper Wire conversion stated in FPCN20649.	
List of affected Standard Parts:	
NSS30100LT1G NSS30101LT1G	

TEM001153 Rev. C Page 1 of 1